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Light-Emitting Diodes: Research, Manufacturing, and Applications XI

**Klaus P. Streubel
Heonsu Jeon**
Editors

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Contents

vii *Conference Committee*

NOVEL TECHNOLOGIES FOR LEDs

- 648604 **Fundamental mechanisms of electroluminescence refrigeration in heterostructure light-emitting diodes** [6486-03]
S.-Q. Yu, J.-B. Wang, D. Ding, S. R. Johnson, D. Vasileska, Y.-H. Zhang, Arizona State Univ. (USA)
- 648605 **Nonperiodic binary optical structures for enhancing light extraction of emitters** [6486-04]
L. Hong, X. Hu, T. Yu, T. Dai, Z. Zhang, J. Xu, G. Zhang, Peking Univ. (China)
- 648606 **High light-extraction efficiency in GaInN light-emitting diode with pyramid reflector** [6486-05]
J.-Q. Xi, H. Luo, J. K. Kim, E. F. Schubert, Rensselaer Polytechnic Institute (USA)
- 648607 **LED engine hosted on a THS** [6486-06]
M. Checchetti, micrOptronics (Italy)

FABRICATION OF LEDs AND OLEDs

- 64860A **Dicing of high-power white LEDs in heat sinks with the water jet-guided laser** [6486-09]
T. A. Mai, R. Housh, A. Brulé, B. Richerzhagen, Synova S.A. (Switzerland)
- 64860C **Integration of high-efficiency PIN organic light-emitting devices in lighting and optoelectronic applications (Invited Paper)** [6486-11]
J. Amelung, M. Toerker, Y. Tomita, D. Kreye, C. Grillberger, U. Vogel, A. Elgner, M. Eritt, Ch. May, U. Todt, C. Luber, R. Hermann, Ch. Zschippang, Fraunhofer Institute for Photonic Microsystems (Germany); K. Leo, Fraunhofer Institute for Photonic Microsystems (Germany) and Technical Univ. Dresden (Germany)

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The CID number appears on each page of the manuscript. The complete citation is used on the first page, and an abbreviated version on subsequent pages.

ORGANIC LEDs

- 64860D **New architectures for high-performance polymer light-emitting diodes introducing a solution-processed titanium oxide layer (Invited Paper)** [6486-12]
S. H. Kim, J. Y. Kim, S. H. Park, K. Lee, Pusan National Univ. (South Korea)
- 64860E **OLED lighting: light where it never has been before (Invited Paper)** [6486-13]
M. Klein, K. Heuser, F. Schindler, B. Krummacher, T. Dobbertin, Osram Opto Semiconductors GmbH (Germany); R. Pätzold, C. Gärditz, Siemens AG (Germany)
- 64860F **See-through OLED displays (Invited Paper)** [6486-14]
W. Kowalsky, P. Görrn, J. Meyer, M. Kröger, H.-H. Johannes, T. Riedl, Technische Univ. Braunschweig (Germany)
- 64860G **Fabrication of polymer LEDs by resonant infrared pulsed laser ablation** [6486-15]
S. L. Johnson, C. T. Bowie, B. Ivanov, Vanderbilt Univ. (USA); H. K. Park, AppliFlex, LLC (USA); R. F. Haglund, Jr., Vanderbilt Univ. (USA)
- 64860H **Employing a 2D surface grating to improve light out coupling of a substrate emitting organic LED** [6486-16]
P. Vandersteegen, Univ. Gent-IMEC (Belgium); A. U. Nieto, Univ. Gent (Belgium); C. Van Buggenhout, S. Verstuyft, P. Bienstman, P. Debackere, Univ. Gent-IMEC (Belgium); K. Neyts, Univ. Gent (Belgium); R. Baets, Univ. Gent-IMEC (Belgium)

LED CHARACTERIZATION AND RELIABILITY

- 64860J **Measurement of the internal quantum efficiency of InGaN quantum wells** [6486-18]
A. Laubsch, M. Sabathil, G. Bruederl, Osram Opto Semiconductors (Germany); J. Wagner, Fraunhofer-Institut für Angewandte Festkörperphysik (Germany); M. Strassburg, E. Baur, Osram Opto Semiconductors (Germany); H. Braun, U. T. Schwarz, Univ. of Regensburg (Germany); A. Lell, S. Lutgen, N. Linder, R. Oberschmid, B. Hahn, Osram Opto Semiconductors (Germany)
- 64860K **Design and implementation of real-time LED spatial radiance measurement systems** [6486-19]
G.-W. Chang, Z.-M. Yeh, C.-C. Liao, National Taiwan Normal Univ. (Taiwan)
- 64860L **Studies of InGaN LEDs degradation** [6486-20]
O. I. Rabinovich, F. I. Manyakhin, E. K. Naimi, Moscow State Institute of Steel and Alloys, Technological Univ. (Russia); S. G. Nikiforov, ATV Outdoor Systems (Russia); V. P. Sushkov, I. G. Ermoshin, Moscow State Institute of Steel and Alloys, Technological Univ. (Russia); A. V. Shishov, Acol Technologies SA (Russia)
- 64860M **Prediction of intensity and color degradation of LEDs** [6486-21]
M. Bürmen, F. Pernuš, B. Likar, Univ. of Ljubljana (Slovenia)
- 64860N **Thermally induced stresses resulting from coefficient of thermal expansion differentials between an LED sub-mount material and various mounting substrates** [6486-22]
C. DeMilo, C. Bergad, R. Forni, T. Brukilacchio, Innovations in Optics, Inc. (USA)

PHOTONIC CRYSTALS: LED MODELING

- 64860Q **Manufacturing implications for photonic crystal patterning using imprint lithography (Invited Paper)** [6486-25]
C. Jones, D. Lentz, G. Doyle, M. Miller, M. Ganapathisubramanian, X. Lu, D. Resnick, D. L. LaBrake, Molecular Imprints, Inc. (USA)
- 64860R **Photonic quasi-crystal LEDs: design, modeling, and optimisation (Invited Paper)** [6486-26]
M. D. B. Charlton, Univ. of Southampton (United Kingdom) and Mesophotonics Ltd. (United Kingdom); M. E. Zoorob, T. Lee, Mesophotonics Ltd. (United Kingdom)
- 64860S **Modeling of GaN-based resonant-cavity light-emitting diode** [6486-27]
Z. S. Li, Z. Q. Li, Crosslight Software, Inc. (Canada); R.-H. Horng, National Chung Hsing Univ. (Taiwan)
- 64860T **A generalized 2D and 3D white LED device simulator integrating photon recycling and luminescent spectral conversion effects** [6486-28]
W.-C. Ng, Synopsys, Inc. (USA); G. Létay, Synopsys Switzerland, LLC (Switzerland)

LED MODELING: PHOSPHORS

- 64860U **Statistical analysis and yield management in LED design through TCAD device simulation** [6486-29]
G. Létay, Synopsys Switzerland, LLC (Switzerland); W.-C. Ng, Synopsys, Inc. (USA); L. Schneider, A. Bregy, M. Pfeiffer, Synopsys Switzerland, LLC (Switzerland)
- 64860V **Self-consistent modeling of resonant PL in InGaN SQW LED structure** [6486-30]
M. Sabathil, A. Laubsch, N. Linder, Osram Opto Semiconductors (Germany)
- 64860X **A new wafer level coating technique to reduce the color distribution of LEDs** [6486-32]
B. Braune, K. Petersen, J. Strauss, P. Kromotis, M. Kaempf, Osram Opto Semiconductors (Germany)
- 64860Y **Reference-based optical characterization of glass-ceramic converter for high-power white LEDs** [6486-33]
A. Engel, M. Letz, T. Zachau, E. Pawlowski, K. Seneschal-Merz, T. Korb, D. Enseling, B. Hoppe, U. Peuchert, Schott AG (Germany); J. S. Hayden, Schott North America (USA)

SESSION 7

- 64860Z **Requirements on LEDs for advanced optical systems (Invited Paper)** [6486-34]
J. Reill, A. Wilm, Osram Opto Semiconductors (Germany)
- 648610 **Warm white LEDs lighting over Ra=95 and its applications** [6486-35]
K. Kobashi, T. Taguchi, Yamaguchi Univ. (Japan)
- 648611 **Development of light distribution controllable luminaire using high-power LEDs** [6486-36]
H. Asakawa, Marumo Electric Co., Ltd. (Japan); J. Baba, A. Yaeda, M. Wakaki, Tokai Univ. (Japan)

- 648612 **A novel temperature compensated operation scheme for trichromatic LED backlights** [6486-38]
D.-W. Lee, J.-H. Kim, M.-Y. Park, H.-D. Kim, J.-K. Park, S.-R. Hwang, S.-M. Cho, Samsung Electro-Mechanics Co., Ltd. (South Korea)
- 648613 **Silicon carbide white light LEDs for solid-state lighting** [6486-49]
S. Bet, College of Optics and Photonics, Univ. of Central Florida (USA); N. Quick, Applicote Associates, LLC (USA); A. Kar, College of Optics and Photonics, Univ. of Central Florida (USA)

SESSION 8

- 648614 **Excitonic effects in ZnO nanowires and hollow nanotubes (Invited Paper)** [6486-39]
M. Willander, Linköping Univ. (Sweden) and Gothenburg Univ. (Sweden); Y. E. Lozovik, Institute of Spectroscopy (Russia); Q. X. Zhao, O. Nur, Linköping Univ. (Sweden); Q.-H. Hu, P. Klason, Gothenburg Univ. (Sweden)
- 648616 **Fabrication of high-power AlInGaP-based red light emitting diodes with novel package by electroplating** [6486-41]
K. C. Chen, Y. K. Su, J. Q. Huang, National Cheng Kung Univ. (Taiwan); C. L. Lin, Kun Shan Univ. (Taiwan); R. W. Chuang, National Cheng Kung Univ. (Taiwan)
- 648617 **Low-resistance and high-reflectivity Aluminum-based reflectors for p-GaN flip process** [6486-42]
S. W. Chae, K. Y. Ko, D. W. Kim, S. M. Hwang, H. J. Park, J. W. Kim, Y. C. Kim, Samsung Electro-Mechanics Co., Ltd. (South Korea)

POSTER SESSION

- 64861A **Developing a new supplemental lighting device with ultra-bright white LED for vegetables** [6486-37]
Y. Hu, P. Li, J. Jiang, Jiangsu Univ. (China)
- 64861B **Development of 140-inch autostereoscopic display by use of full-color LED panel** [6486-45]
H. Nishimura, T. Abe, H. Yamamoto, Y. Hayasaki, N. Nishida, The Univ. of Tokushima (Japan)
- 64861C **High refractive index nanoparticle-loaded encapsulants for light-emitting diodes** [6486-48]
F. W. Mont, J. K. Kim, M. F. Schubert, H. Luo, E. F. Schubert, R. W. Siegel, Rensselaer Polytechnic Institute (USA)

Author Index

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Novel Technologies for LEDs

Klaus P. Streubel, Osram Opto Semiconductors GmbH (Germany)

Fabrication of LEDs and OLEDs

Gerd Bacher, Universität Duisburg-Essen (Germany)

Organic LEDs

Michael Heuken, Aixtron AG (Germany)

LED Characterization and Reliability

Kurt J. Linden, Spire Corporation (USA)

Photonic Crystals: LED Modeling

Ross P. Stanley, Centre Suisse d'Electronique et de Microtechnique SA
(Switzerland)

LED Modeling: Phosphors

Li-Wei Tu, National Sun Yat-Sen University (Taiwan)

Session 7

Heonsu Jeon, Seoul National University (South Korea)

Session 8

Klaus P. Streubel, Osram Opto Semiconductors GmbH (Germany)